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PATENT

2881

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Shing M. Lee

Attorney Docket No.: KLA1P012/P647US

Application No.: 09/695,726

Examiner: Fernandez, K.

Filed: October 23, 2000

Group: 2881

Title: FILM THICKNESS MEASUREMENT
USING ELECTRON-BEAM INDUCED
X-RAY MICROANALYSIS

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail to: Commissioner for Patents, Washington, DC 20231 on March 21, 2002.

Signed: Lara M. Nelson

Lara M. Nelson

AMENDMENT TRANSMITTAL

Commissioner for Patents
Washington, DC 20231

Sir:

Transmitted herewith is an Amendment in the above-identified application.

The fee has been calculated as shown below.

	Claims After Amendment		Highest Previously Paid For	Present Extra	Small Entity Rate Fee	Large Entity Rate Fee
Total Claims	30	MINUS	30	00	x 9 =	x 18 =
Independent Claims	04	MINUS	06	00	x 42 =	x 84 =
Multiple Dependent Claim Present and Fee Not Previously Paid					\$140.00	\$280.00
Total					\$	\$

- ☐ Applicant(s) hereby petition for a _____ month extension(s) of time to respond to the aforementioned Office Action.
- ☒ Applicant(s) believe that no (additional) Extension of Time is required; however, if it is determined that such an extension is required, Applicant(s) hereby petition that such an extension be granted and authorize the Commissioner to charge the required fees for an Extension of Time under 37 CFR 1.136 to Deposit Account No. 500388.
- ☐ Enclosed is our Check No. _____ in the amount of \$_____ to cover the additional claim fee and/or extension of time fees.
- ☒ Please charge the required fees, or any additional fees required to facilitate filing the enclosed response, to Deposit Account No. 500388 (Order No. KLA1P012).

Respectfully submitted,
BEYER WEAVER & THOMAS, LLP

Phillip P. Lee

Phillip P. Lee
Reg. No. 46,866

P.O. Box 778
Berkeley, CA 94704-0778

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#8/A
4/25/02
✓D

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail to: Assistant Commissioner for Patents, Washington, DC 20231 on March 21, 2002.

Printed Name: Lara M. Nelson

Signed: Lara M. Nelson

AMENDMENT A

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir or Madame:

In response to the Office Action dated December 21, 2001, a response to which is due March 21, 2002, please enter the following amendments and consider the following remarks:

IN THE SPECIFICATION

Please amend the specification as follows:

Please replace the paragraph beginning on page 1 line 22 and ending on page 2 line 9 with the following paragraph.

A critical aspect of semiconductor fabrication involves the formation of the multiple conductive layers and liner layers. Each conductive layer includes the metal traces which form the paths along which electronic signals travel within semiconductor devices. Each of the conductive layers, are separated by a dielectric material layer and a liner layer. The dielectric material layer, commonly silicon dioxide, provides electrical insulation between the conductive layers. Portions of

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